

# SOT1064-1

plastic low profile fine-pitch ball grid array package; 84 balls

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	LFPGA84
<b>Package type industry code</b>	LFPGA84
<b>Package style descriptive code</b>	LFPGA (low profile fine-pitch ball grid array)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>IEC package outline code</b>	---
<b>JEDEC package outline code</b>	---
<b>JEITA package outline code</b>	---
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	2-4-2008

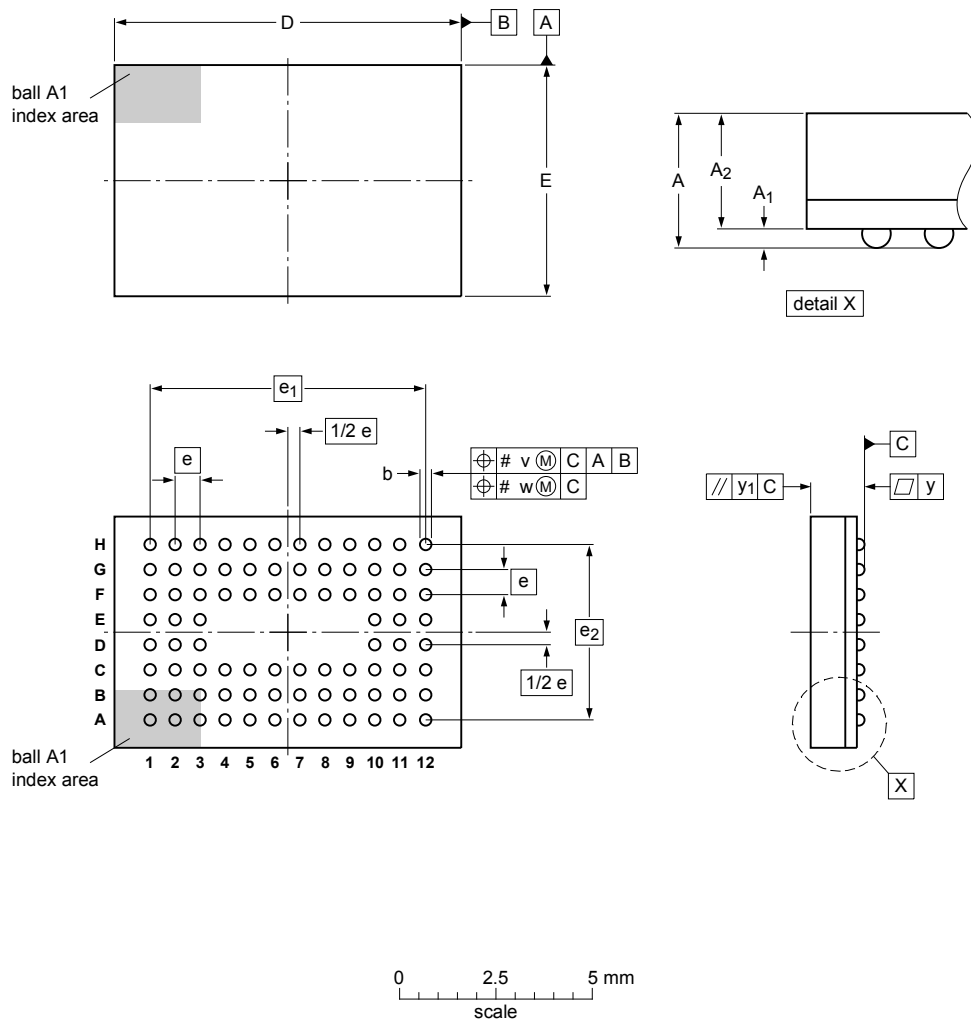
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	8.9	-	9	9.1	mm
E	package width	5.9	-	6	6.1	mm
A	seated height	1.3	-	1.4	1.5	mm
A <sub>2</sub>	package height	1.15	-	1.2	1.25	mm
n <sub>2</sub>	actual quantity of termination	-	-	84	-	



## 2. Package outline

LFBGA84: plastic low profile fine-pitch ball grid array package; 84 balls SOT1064-1



**DIMENSIONS** (mm are the original dimensions)

UNIT		A	A <sub>1</sub>	A <sub>2</sub>	b	D	E	e	e <sub>1</sub>	e <sub>2</sub>	v	w	y	y <sub>1</sub>
mm	max	1.5	0.25	1.25	0.35	9.1	6.1	0.65	7.15	4.55	0.15	0.08	0.08	0.1
	nom	1.4	0.20	1.20	0.30	9.0	6.0							
	min	1.3	0.15	1.15	0.25	8.9	5.9							

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT1064-1	---	---	---			08-03-27 08-04-02

**Fig. 1. Package outline LFBGA84 (SOT1064-1)**

### 3. Soldering

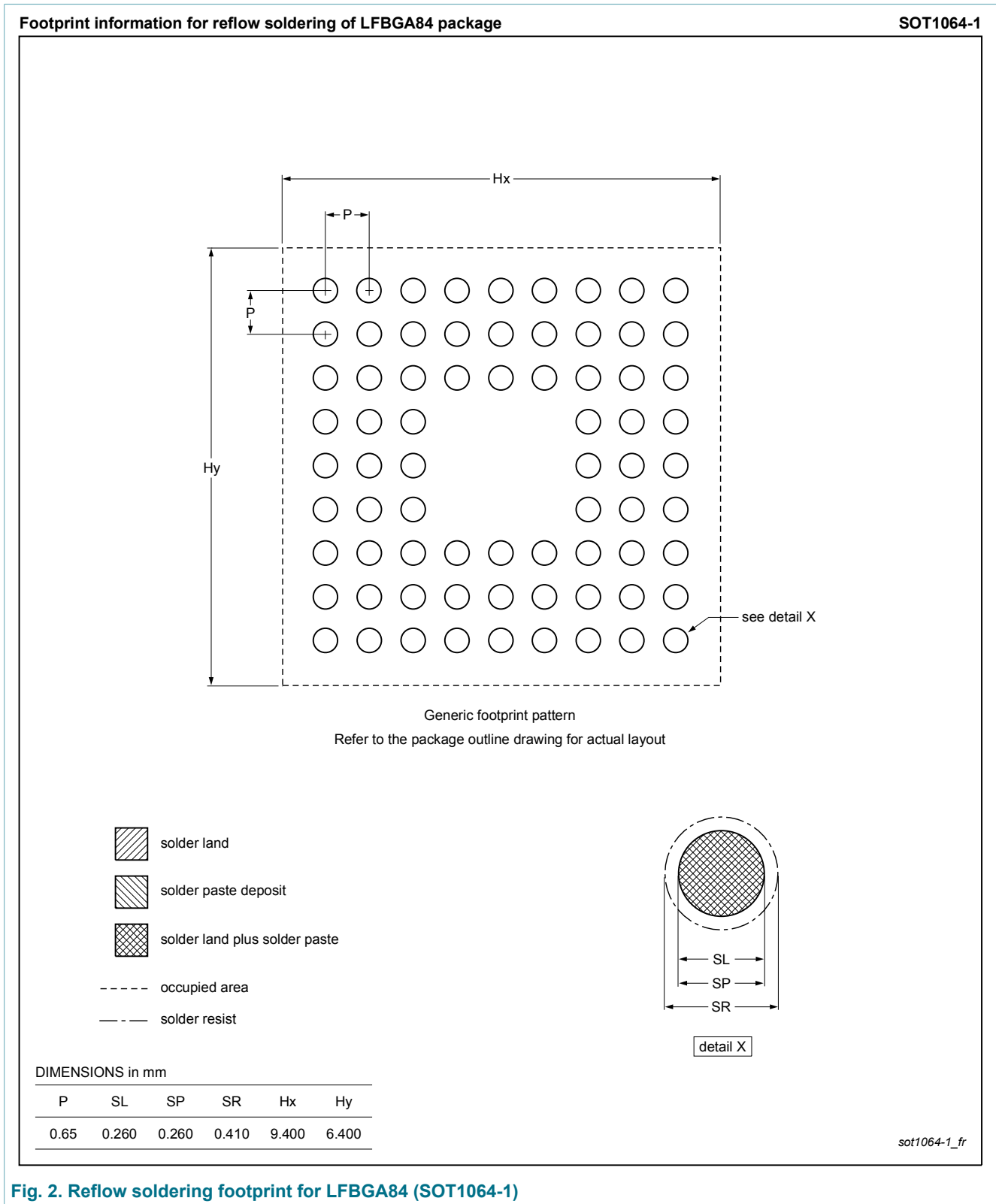


Fig. 2. Reflow soldering footprint for LFBGA84 (SOT1064-1)

## 4. Legal information

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